IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re Application of: Latchford, et al.

erial No.:

09/921,938

Confirmation No.:

Filed: August 2, 2001

PHOTOLITHOGRAPHY SCHEME

USING A SILICON CONTAINING

RESIST

Assistant Commissioner for Patents Washington, D.C. 20231

Group Art Unit:

1752

Examiner:

A. Walke

CERTIFICATE OF MAILING 37 CFR 1.8

I hereby certify that this correspondence is being deposited on January 24, 2002 with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washin on, D.C. 20231.

Signature

Dear Sir:

RESPONSE TO OFFICE ACTION DATED OCTOBER 24, 2001

In response to the Office Action dated October 24, 2001, having a shortened statutory period for response set to expire on January 24, 2002, Applicants request entry and consideration of the following remarks. Although Applicant believes that no fee is due in conjunction with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/4227.P1/DD/BCVD/JW for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Pending Claims:

1. A method for forming a patterned amorphous carbon layer in a multilayer stack, comprising:

depositing an amorphous carbon layer on a substrate;